

In the claims:

Please cancel claims 1-7 and amend claims 8-10 as follows:

Claims 1-7 (canceled).

Claim 8 (currently amended). A fumed silica abrasive useful for polishing tungsten and titanium on a semiconductor wafer wherein the fumed silica has a surface area of greater than 90 m²/g and has been entirely dispersed and diluted in an acidic pH solution.

Claim 9 (currently amended). The fumed silica abrasive of claim 8 wherein the fumed silica has a surface area greater than 130 m²/g.

Claim 10 (currently amended). A composition useful for polishing tungsten and titanium on a semiconductor wafer, the composition containing an abrasive, wherein the abrasive is fumed silica abrasive that has a surface area of greater than 90 m²/g and has been entirely dispersed and diluted in an acidic pH solution.